

General Description

Ultra-FRD module devices are optimized to reduce losses and EMI/RFI in high frequency power conditioning electrical systems.

These diode modules are ideally suited for power converters, motors drives and other applications where switching losses are significant portion of the total losses.

Features

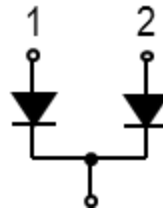
- Repetitive Reverse Voltage : $V_{RRM} = 400V$
- Low Forward Voltage : $V_F(\text{typ.}) = 1.0V$
- Average Forward Current : $I_F(\text{Av.}) = 200A$ @ $T_C = 100^\circ C$
- Ultra-Fast Reverse Recovery Time : $t_{rr}(\text{typ.}) = 40ns$
- Extensive Characterization of Recovery Parameters
- Reduced EMI and RFI
- Non Isolation Type Package
- $175^\circ C$ Operating Junction Temperature
- Dual FRD Construction

Applications

- High Speed & High Power converters, Welders
- Various Switching and Telecommunication Power Supply



3DM-2NI
Non Isolation Type



(Common Heat Sink)

Absolute Maximum Ratings @ $T_C = 25^\circ C$ (Per Leg)

Characteristics	Conditions	Symbol	Rating	Unit
Repetitive Peak Reverse Voltage		V_{RRM}	400	V
Reverse DC Voltage		$V_{R(DC)}$	320	V
Average Forward Current	$T_C = 25^\circ C$	$I_{F(AV)}$	400	A
	$T_C = 100^\circ C$		200	A
Surge(non-repetitive) Forward Current	One Half Cycle at 60Hz, Peak Value	I_{FSM}	3300	A
I^2t for Fusing	Value for One Cycle Current, $t_w = 8.3ms$, $T_J = 25^\circ C$ Start	I^2t	45.0×10^3	A^2s
Junction Temperature		T_J	$-40 \sim 175$	$^\circ C$
Maximum Power Dissipation		P_D	1070	W
Storage Temperature		T_{stg}	$-40 \sim 150$	$^\circ C$
Mounting Torque(M6)		-	4.0	N.m
Terminal Torque(M6)	Typical Including Screws	-	3.0	N.m
Weight		-	95	g

Electrical Characteristics @T_c = 25°C(unless otherwise specified)

Characteristics	Conditions		Symbol	Min.	Typ.	Max.	Unit
Cathode Anode Breakdown Voltage	I _R =100uA		V _R	400	-	-	V
Diode Maximum Forward Voltage	I _F =200A	T _C =25 °C	V _{FM}	-	1.0	1.3	V
		T _C =100 °C		-	0.9	-	
Diode Peak ReverseRecovery Current	T _c =100 °C, V _{RRM} applied	T _C =100 °C	I _{RRM}	-	-	1.0	mA
Diode Reverse Recovery Time	I _F =1A,V _R =30V di/dt = -400A/uS	T _C =25 °C	t _{rr}	-	40	50	ns
Diode Reverse Recovery Time	I _F =200A,V _R =200V di/dt = -400A/uS	T _C =25 °C	t _{rr}	-	100	-	ns
		T _C =100 °C		-	130	-	

Thermal Characteristics

Characteristics	Conditions	Symbol	Min.	Typ.	Max.	Unit
Thermal Resistance(Non-Isolation Type)	Junction to Case	R _{th(j-c)}	-	-	0.14	°C/W

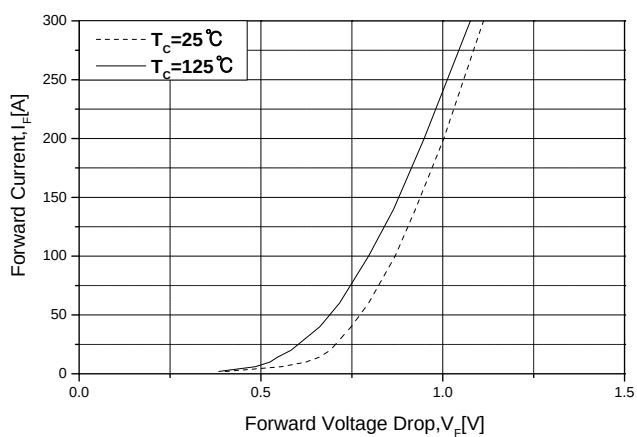


Fig.1 Typical Forward Voltage Drop vs. Instantaneous Forward Current

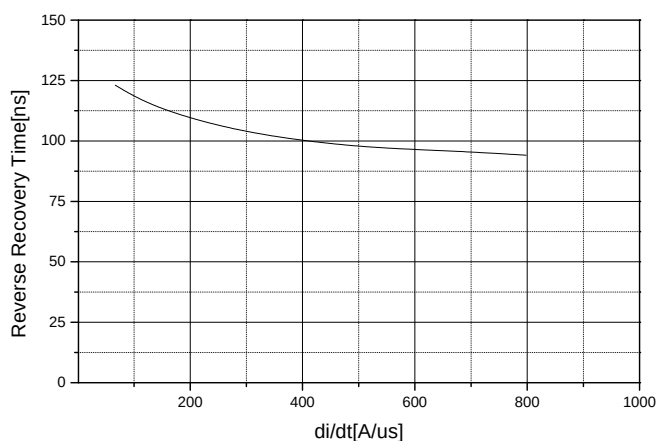


Fig.2 Typical Reverse Recovery Time Vs. $-di/dt$

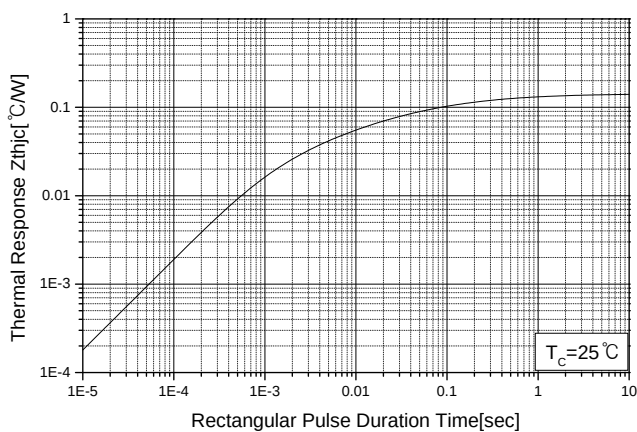


Fig.3 Transient Thermal Impedance (Z_{thjc}) Characteristics

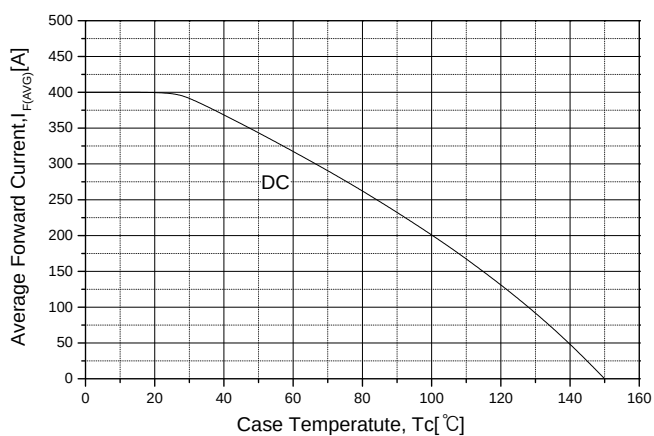
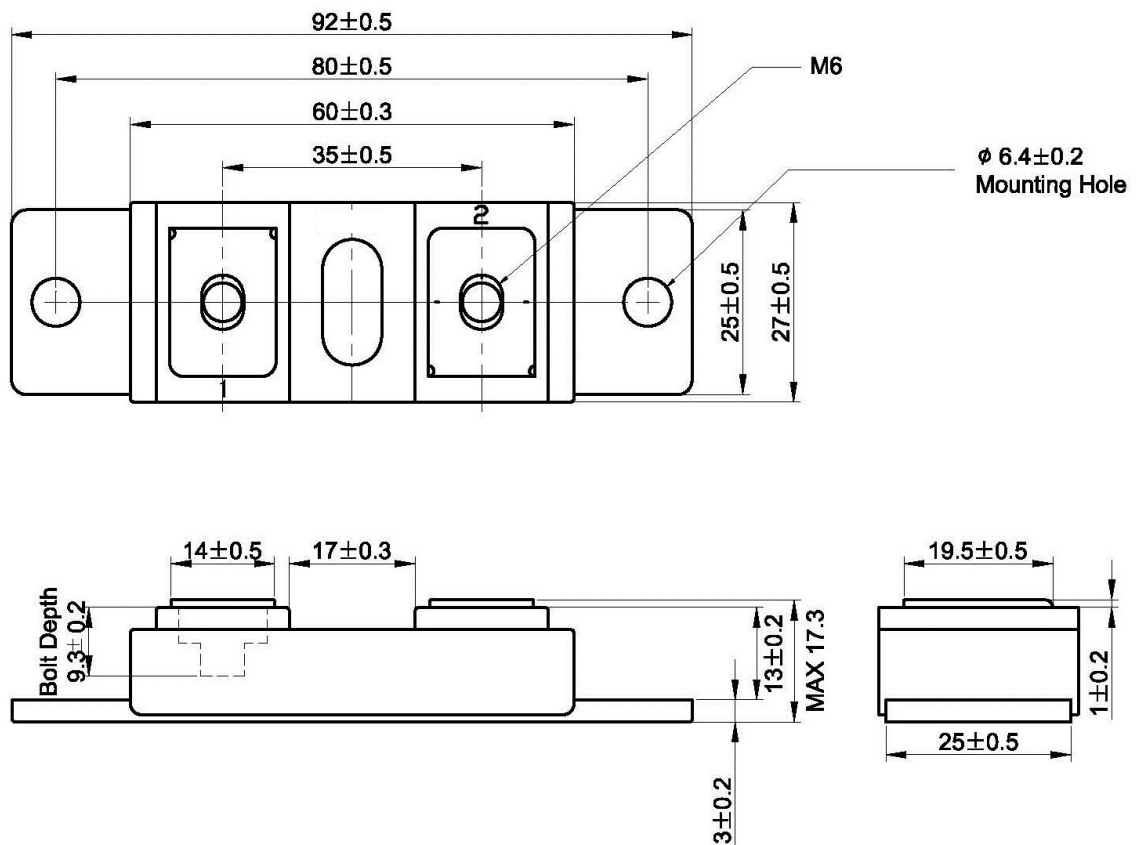


Fig.4 Forward Current Derating Curve

Package Dimension

3DM-2NI

Dimensions are in millimeters, unless otherwise specified



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